

### Super-Fast recovery rectifier diode in bare die form

## Features:

- Very low reverse recovery time
- High efficiency, low switching losses
- Very low forward voltage drop
- Controlled avalanche with peak reverse power capability
- High reliability tested grades.

# Ordering Information

The following part suffixes apply:

- No suffix MIL-STD-750 /2073 Visual Inspection
- "H" MIL-STD-750 /2073 Visual Inspection + MIL-PRF-38534 Class H LAT
- "K" MIL-STD-750 /2073 Visual Inspection + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

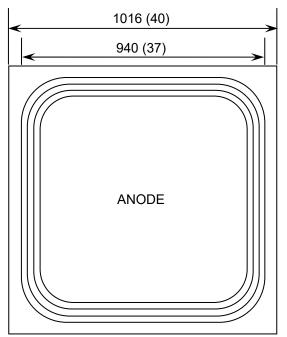
For further information on LAT process flows see below.

www.siliconsupplies.com\quality\bare-die-lot-qualification

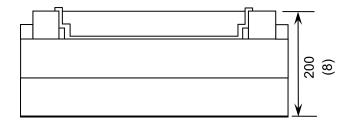
# Supply Formats:

- Default Die in Waffle Pack (100 per tray capacity)
- Sawn Wafer on Tape By specific request
- Unsawn Wafer By specific request
- With additional electrical selection By specific request

## Die Dimensions in µm (mils)



CHIP BACKSIDE IS CATHODE



# **Mechanical Specification**

Die Size (Unsawn)	1016 x 1016 40 x 40	µm mils	
Anode Pad Size	940 x 940 37 x 37	µm mils	
Die Thickness	200 (±20) 7.87 (±0.79)	µm mils	
Top Metal Composition	Al		
Back Metal Composition	Ti/Ni/Ag		



**Rev 1.0** 

07/12/20



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# Absolute Maximum Ratings T<sub>J</sub> = 25°C unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Working peak reverse voltage	V <sub>RWM</sub>	150	V
Repetitive peak reverse voltage	V <sub>RRM</sub>	150	V
Average forward rectified current	I <sub>F(AV)</sub> , T <sub>J</sub> = 75°C	2.5	Δ
	I <sub>F(AV)</sub> , T <sub>A</sub> = 55°C	1	
Peak forward surge current <sup>1</sup>	I <sub>FSM</sub>	35	A
Operating Junction temperature	TJ	-55 to 175	C°
Storage Temperature Range	T <sub>STG</sub>	-65 to 200	C°

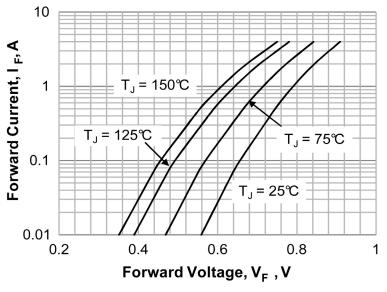
### Electrical Characteristics T<sub>J</sub> = 25°C unless otherwise stated

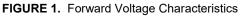
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Breakdown Voltage	V <sub>BR</sub>	I <sub>BR</sub> = 100μA	160	-	-	V
Maximum instantaneous forward voltage <sup>1</sup> V <sub>F</sub>		I <sub>F</sub> = 1A	-	-	0.875	
	VF	I <sub>F</sub> = 1A, T <sub>J</sub> = 125°C	-	-	0.800	V
		I <sub>F</sub> = 2.5A	-	-	0.975	
Maximum reverse leakage current $I_{RM} @ V_{F}$		V <sub>RWM</sub> = 150V, T <sub>J</sub> = 25°C	-	-	1	μA
		V <sub>RWM</sub> = 150V, T <sub>J</sub> = 125°C	-	-	175	
Maximum reverse recovery time	t <sub>rr</sub>	$I_F = 0.5A, I_{RM} = 0.5A, I_{R(REC)} = 0.05A$	-	-	25	ns
Junction Capacitance	CJ	$\label{eq:VR} \begin{array}{c} V_{\text{R}} = 10 \text{V},  T_{\text{J}} = 25^{\circ}\text{C},  f_{\text{SIG}} = 1 \text{MHz}, \\ V_{\text{SIG}} = 50 \text{mV}  (\text{p-p}) \end{array}$	-	-	25	pF

1.  $T_A = 25^{\circ}C \otimes I_0 = 1A$  and  $V_{RWM} = rated$ , 8.3 ms surges at 1minute intervals.

2. Pulse Width = 3.8ms

## Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise stated









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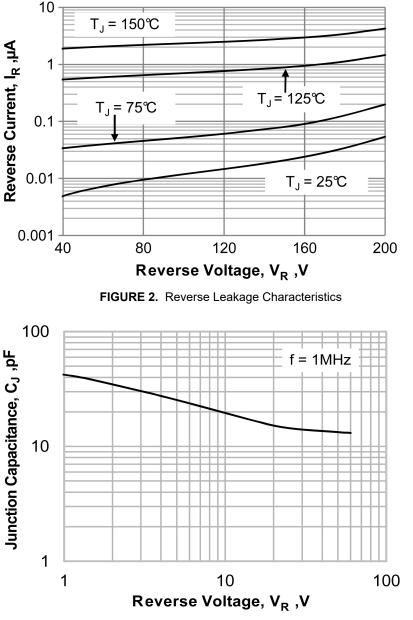


FIGURE 3. Typical Junction Capacitance

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